

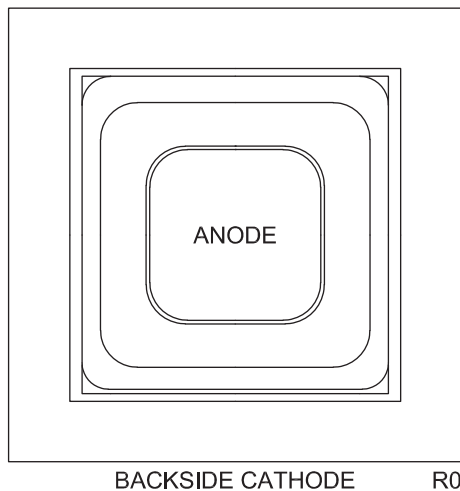
PROCESS CPZ37R
Transient Voltage Suppressor
12 Volt TVS Chip



PROCESS DETAILS

Die Size	6.7 x 6.7 MILS
Die Thickness	3.54 MILS
Anode Bonding Pad Area	4.3 x 4.3 MILS
Top Side Metalization	Al - 13,000Å
Back Side Metalization	Au-As/Ag - 13,000Å/6,000Å

GEOMETRY



GROSS DIE PER 5 INCH WAFER

368,512

PRINCIPAL DEVICE TYPE

CTLTVS12

R0 (16-March 2012)